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TAPE AND REEL TYPE LED LAMPS

LY2040/TRS-X

DATA SHEET

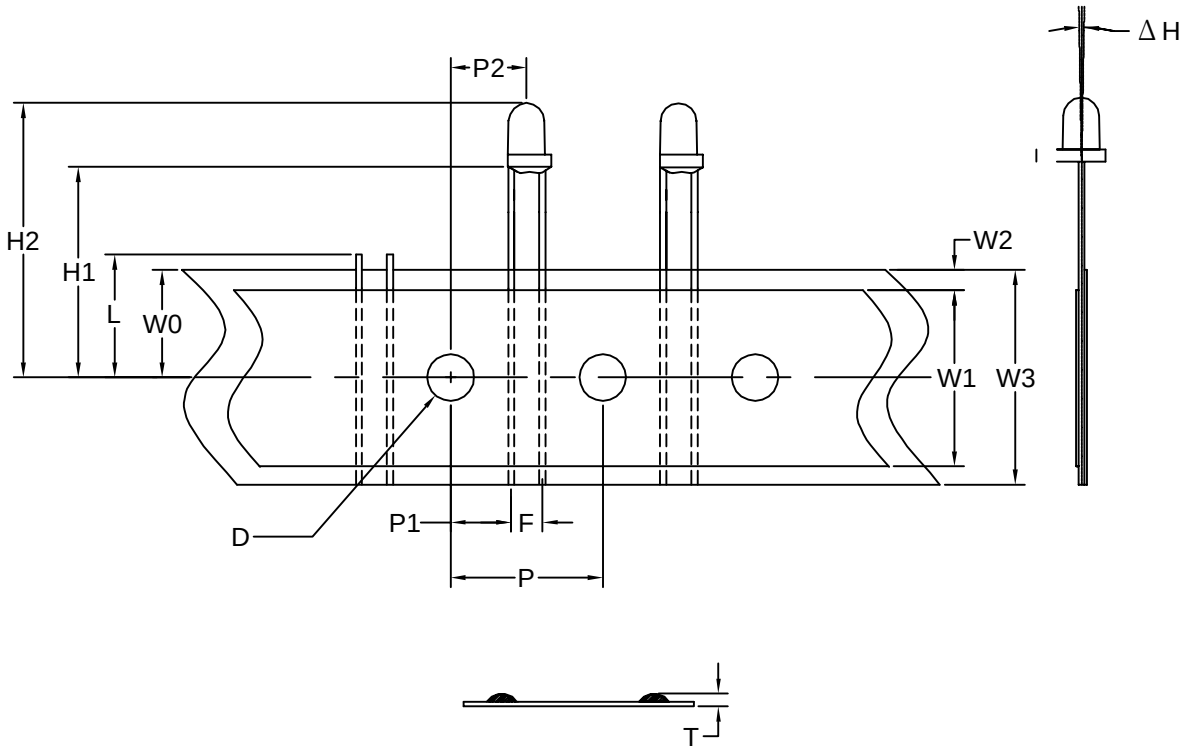
DOC. NO : QW0905-LY2040/TRS-X

REV. : A

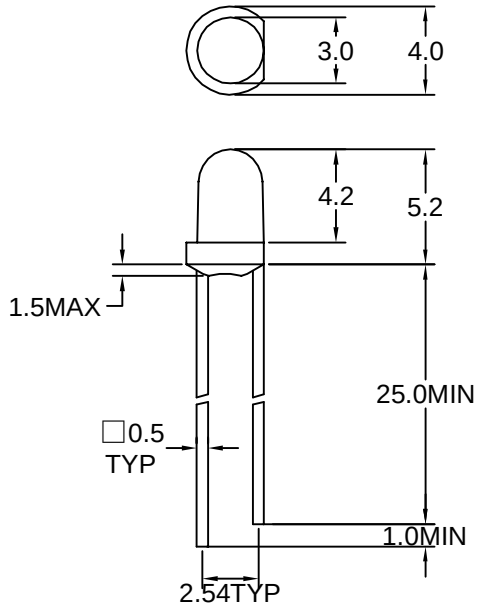
DATE : 31 - Mar. - 2005

PART NO. LY2040/TRS-X

Package Dimensions



LY2040



Note : 1.All dimension are in millimeter tolerance is ±0.25mm unless otherwise noted.
2.Specifications are subject to change without notice.

Absolute Maximum Ratings at Ta=25 ℃

Parameter	Symbol	Ratings	UNIT
		Y	
Forward Current	IF	20	mA
Peak Forward Current Duty 1/10@10KHz	IFP	80	mA
Power Dissipation	PD	60	mW
Reverse Current @5V	Ir	10	μA
Operating Temperature	Topr	-40 ~ +85	℃
Storage Temperature	Tstg	-40 ~ +100	℃
Soldering Temperature	Tsol	Max 260℃ for 5 sec Max (2mm from body)	

Typical Electrical & Optical Characteristics (Ta=25 ℃)

PART NO	MATERIAL	COLOR		Peak wave length λ Pnm	Spectral halfwidth △λ nm	Forward voltage @20mA(V)		Luminous intensity @10mA(mcd)		Viewing angle 2θ 1/2 (deg)
		Emitted	Lens			Min.	Max.	Min.	Typ.	
LY2040/TRS-X	GaAsP/GaP	Yellow	Yellow Diffused	585	35	1.7	2.6	8.0	20	36

Note : 1.The forward voltage data did not including ±0.1V testing tolerance.
2. The luminous intensity data did not including ±15% testing tolerance.

PART NO. LY2040/TRS-X

· Dimensions Symbol Information

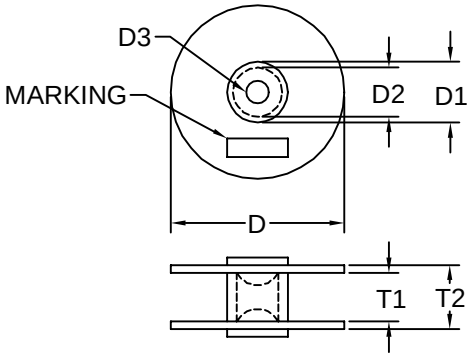
SYMBOL ITEMS	OPTION CODE	SYMBOL	SPECIFICATIONS			
			Minimum		Maximum	
			mm	inch	mm	inch
Tape Feed Hole Diameter	-------	D	3.8	0.15	4.2	0.17
Component Lead Pitch	-------	F	2.3	0.09	3.0	0.12
Front-To-Rear Deflection	-------	△H	-------	-------	2.0	0.08
Feed Hole To Bottom Of Component	TRS-1	H1	17.5	0.69	18.5	0.73
	TRS-2		21.5	0.85	22.5	0.89
	TRS-3		25.5	1.0	26.5	1.04
	TRS-4		27.5	1.08	28.5	1.12
	TRS-5		22.5	0.89	23.5	0.93
	TRS-6		19.9	0.78	20.9	0.82
	TRS-7		24.0	0.94	25.0	0.98
	TRS-8		24.5	0.96	25.5	1.0
	TRS-9		19.0	0.75	20.0	0.79
	TRS-10		18.4	0.72	19.4	0.76
Feed Hole To Overall Component Height	-------	H2	-------	-------	36	1.42
Lead Length After Component Height	-------	L	W0		11.0	0.43
Feed Hole Pitch	-------	P	12.4	0.49	13.0	0.51
Lead Location	-------	P1	4.4	0.17	5.8	0.23
Center Of Component Location	-------	P2	5.1	0.2	7.7	0.3
Overall Taped Package Thickness	-------	T	-------	-------	1.42	0.06
Feed Hole Location	-------	W0	8.5	0.33	9.75	0.38
Adhesive Tape Width	-------	W1	14.5	0.57	15.5	0.61
Adhesive Tape Position	-------	W2	0	0	4.0	0.16
Tape Width	-------	W3	17.5	0.69	19.0	0.75

REMARK:TRS=Tape And Reel Straight Leads

· Dimensions Symbol Information

Description	Symbol	Specification			
		minimum		maxmum	
		mm	inch	mm	inch
Reel Diameter	D	78.2	3.08	380	14.96
Core Diameter	D1	34.9	1.37	102	4.02
Hub Recess Inside Diameter	D2	28.6	1.13	88.0	3.46
Arbor Hole Diameter	D3	13.8	0.54	38.1	1.5
Overall Reel Thickness	T2			57.2	2.25
Iside Reel Flange Thickness	T1	30.0	1.18	50.0	1.97
Quantity/Reel	2000PCS				

· Package Dimensions



Typical Electro-Optical Characteristics Curve

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Fig.1 Forward current vs. Forward Voltage

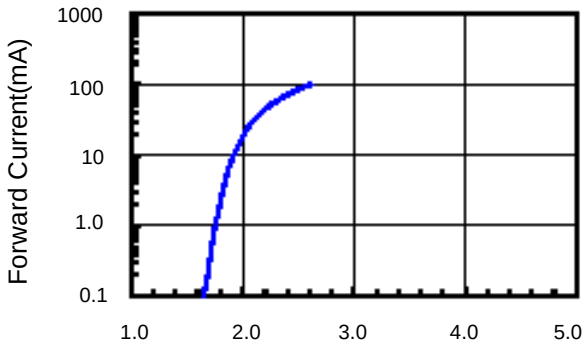


Fig.2 Relative Intensity vs. Forward Current

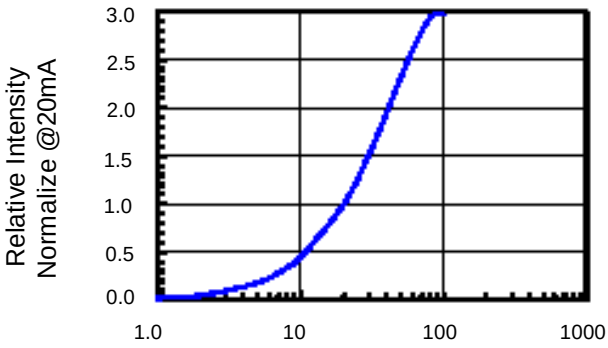


Fig.3 Forward Voltage vs. Temperature

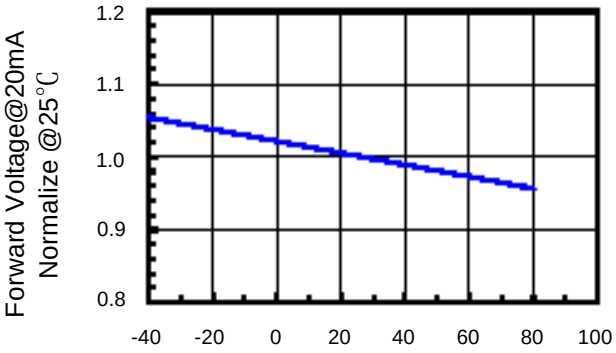


Fig.4 Relative Intensity vs. Temperature

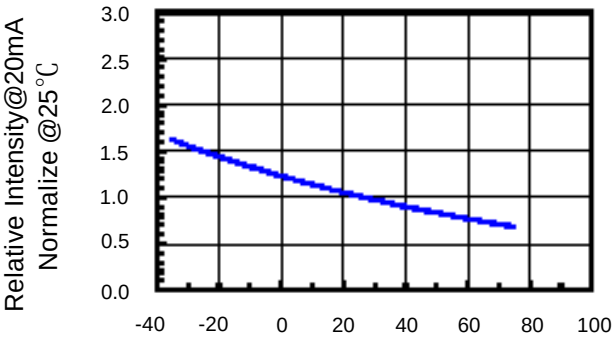


Fig.5 Relative Intensity vs. Wavelength

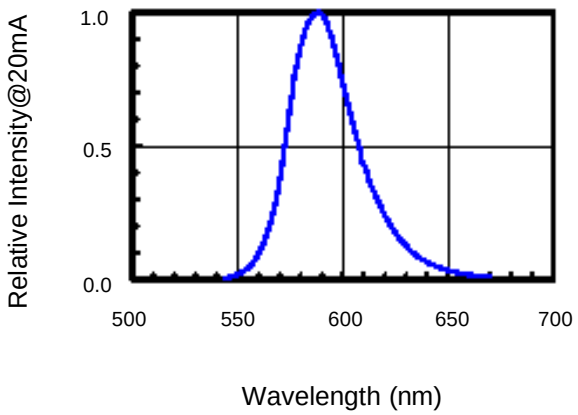
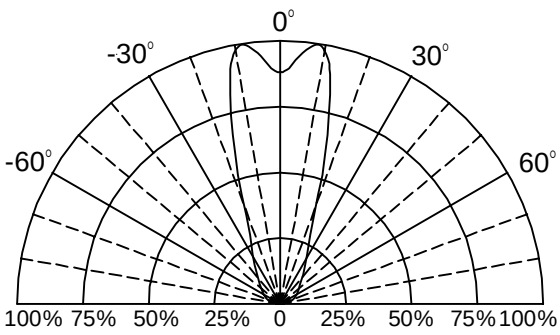


Fig.6 Directivity Radiation



Reliability Test:

Test Item	Test Condition	Description	Reference Standard
Operating Life Test	1.Under Room Temperature 2.If=20mA 3.t=1000 hrs (-24hrs, +72hrs)	This test is conducted for the purpose of detemining the resisance of a part in electrical and themal stressed.	MIL-STD-750: 1026 MIL-STD-883: 1005 JIS C 7021: B-1
High Temperature Storage Test	1.Ta=105℃±5℃ 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under ondition of hogh temperature for hours.	MIL-STD-883:1008 JIS C 7021: B-10
Low Temperature Storage Test	1.Ta=-40℃±5℃ 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of low temperature for hours.	JIS C 7021: B-12
High Temperature High Humidity Test	1.Ta=65℃±5℃ 2.RH=90%~95% 3.t=240hrs±2hrs	The purpose of this test is the resistance of the device under tropical for hous.	MIL-STD-202:103B JIS C 7021: B-11
Thermal Shock Test	1.Ta=105℃±5℃&-40℃±5℃ (10min) (10min) 2.total 10 cycles	The purpose of this is the resistance of the device to sudden extreme changes in high and low temperature.	MIL-STD-202: 107D MIL-STD-750: 1051 MIL-STD-883: 1011
Solder Resistance Test	1.T.Sol=260℃±5℃ 2.Dwell time= 10±1sec.	This test intended to determine the thermal characteristic resistance of the device to sudden exposures at extreme changes in temperature when soldering the lead wire.	MIL-STD-202: 210A MIL-STD-750: 2031 JIS C 7021: A-1
Solderability Test	1.T.Sol=230℃±5℃ 2.Dwell time=5±1sec	This test intended to see soldering well performed or not.	MIL-STD-202: 208D MIL-STD-750: 2026 MIL-STD-883: 2003 JIS C 7021: A-2